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Chang et al.

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(54) **LIGHT EMITTING DIODE PACKAGE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/180**

(58) **Field of Classification Search** D13/180; D26/2; 257/79, 80, 81, 88, 89, 95, 98, 99, 257/100, E33.058; 313/483, 498, 500; 362/555, 362/800

See application file for complete search history.

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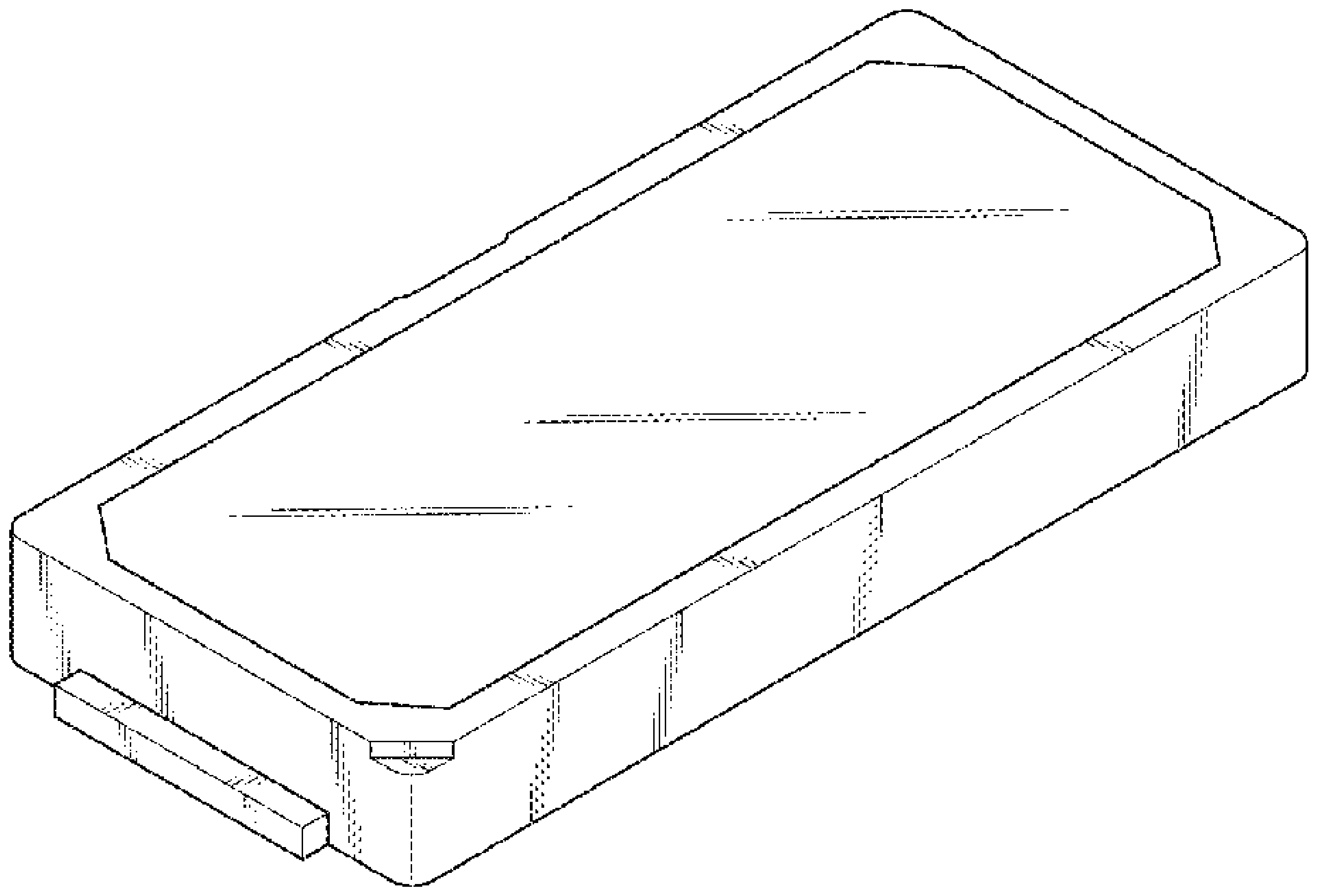
(57) **CLAIM**

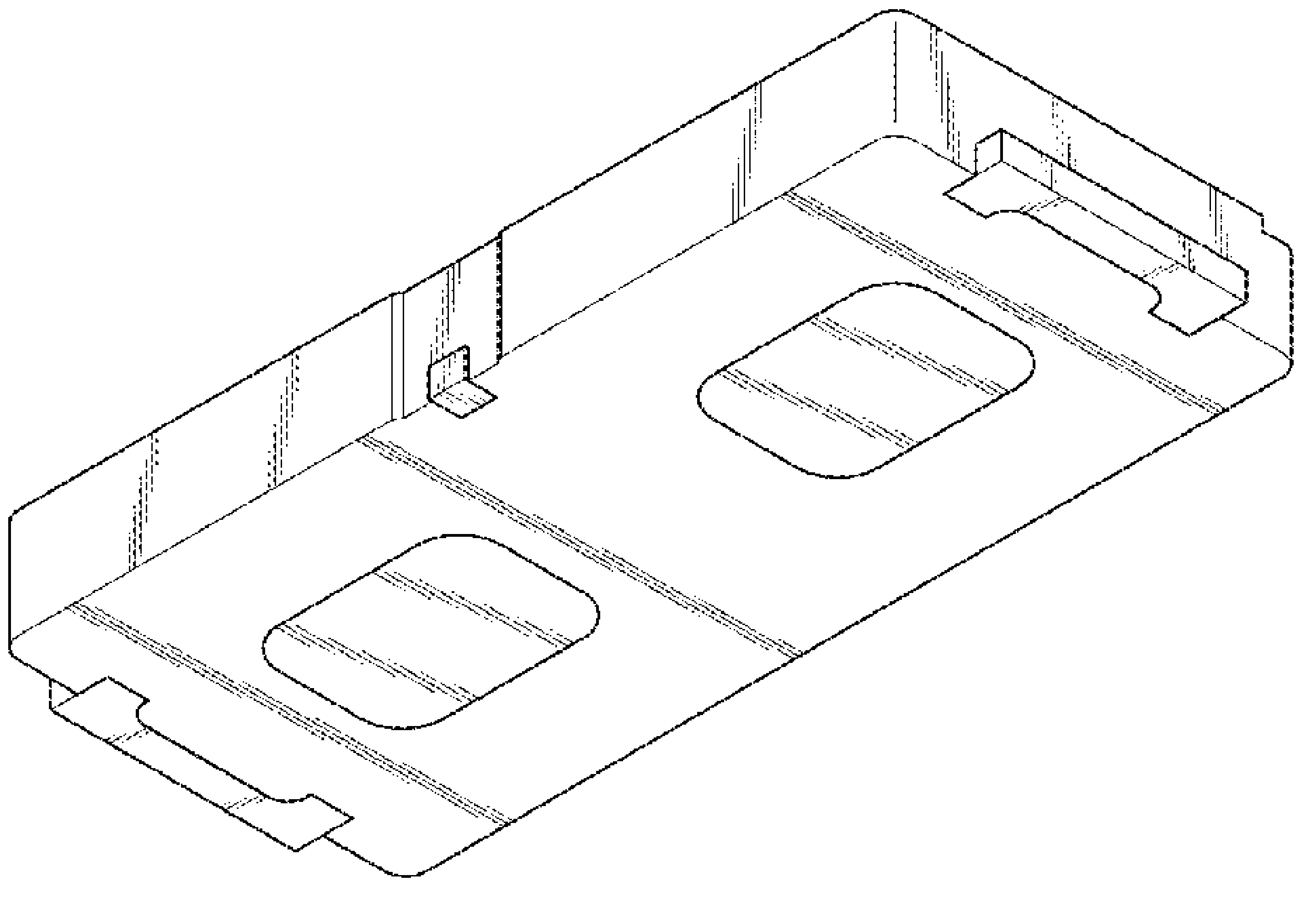
The ornamental design for light emitting diode package, as shown and described.

DESCRIPTION

FIG. **1** is a front perspective view of light emitting diode package showing the new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof;
FIG. **6** is a top plan view thereof;
FIG. **7** is a bottom plan view thereof; and,
FIG. **8** is another elevational view thereof.

1 Claim, 8 Drawing Sheets





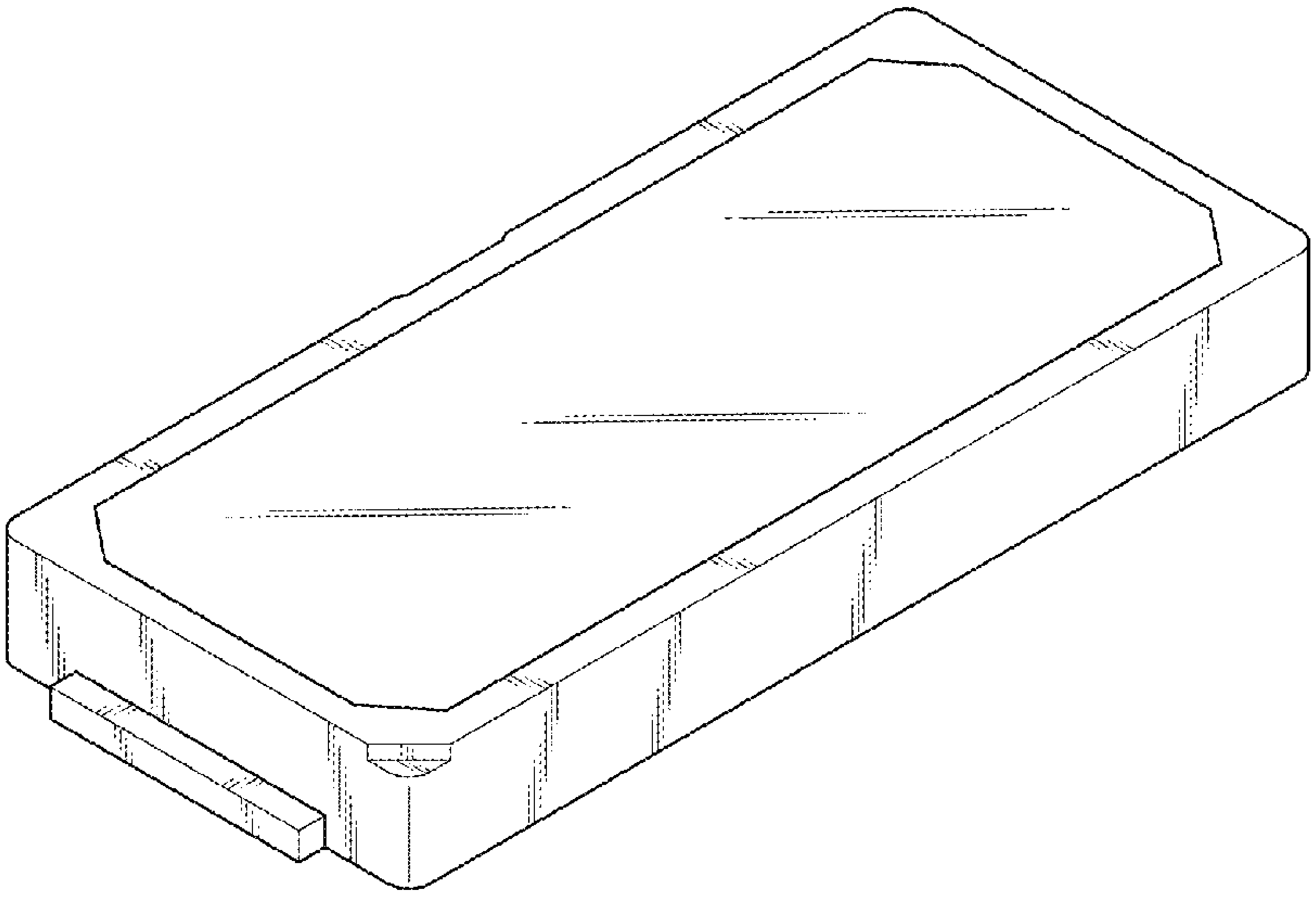


FIG.1

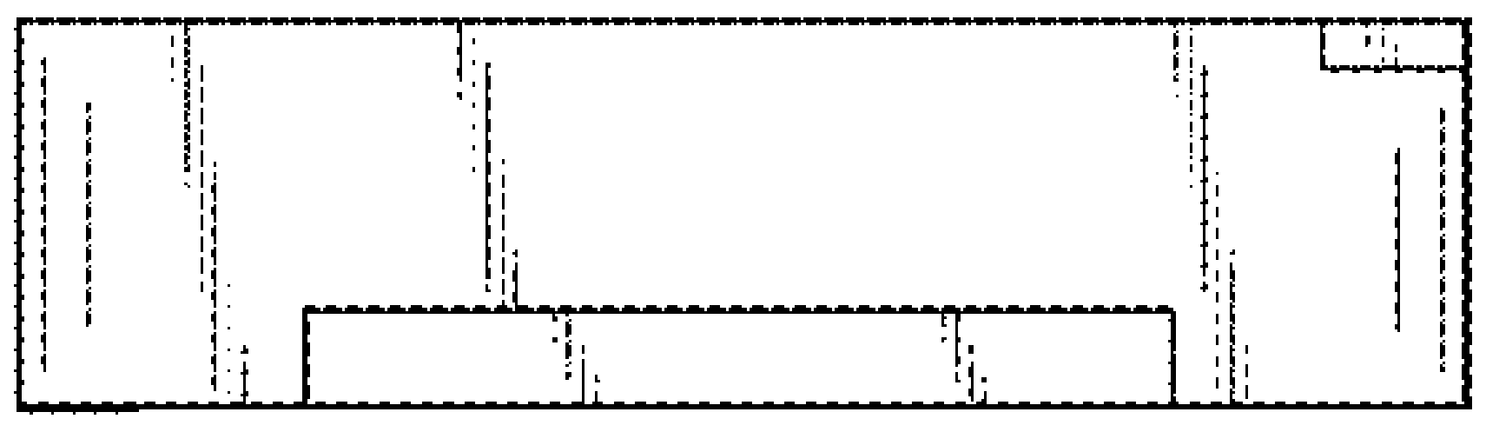


FIG.2

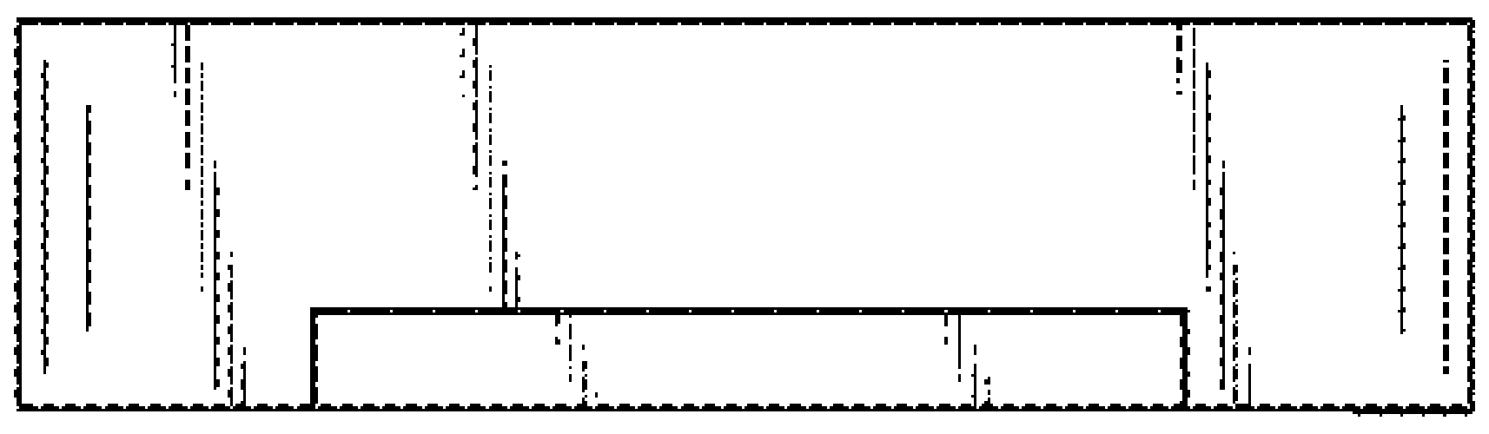


FIG.3

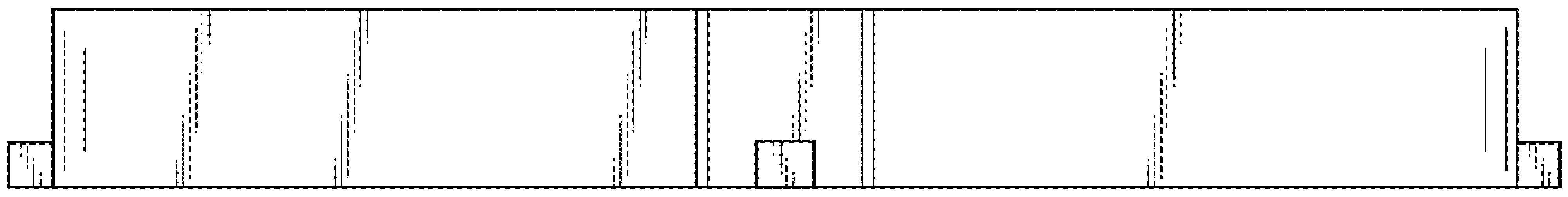


FIG.4

FIG.5

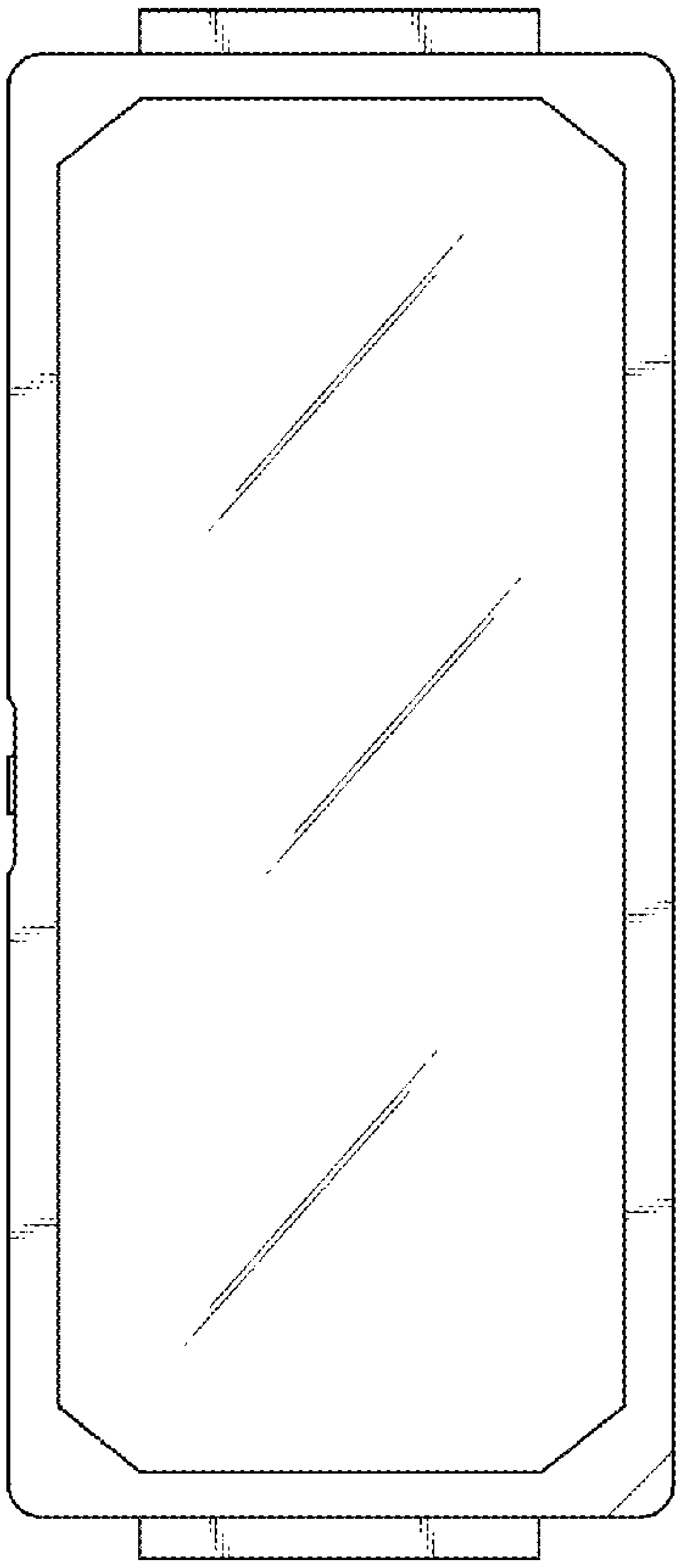


FIG.6

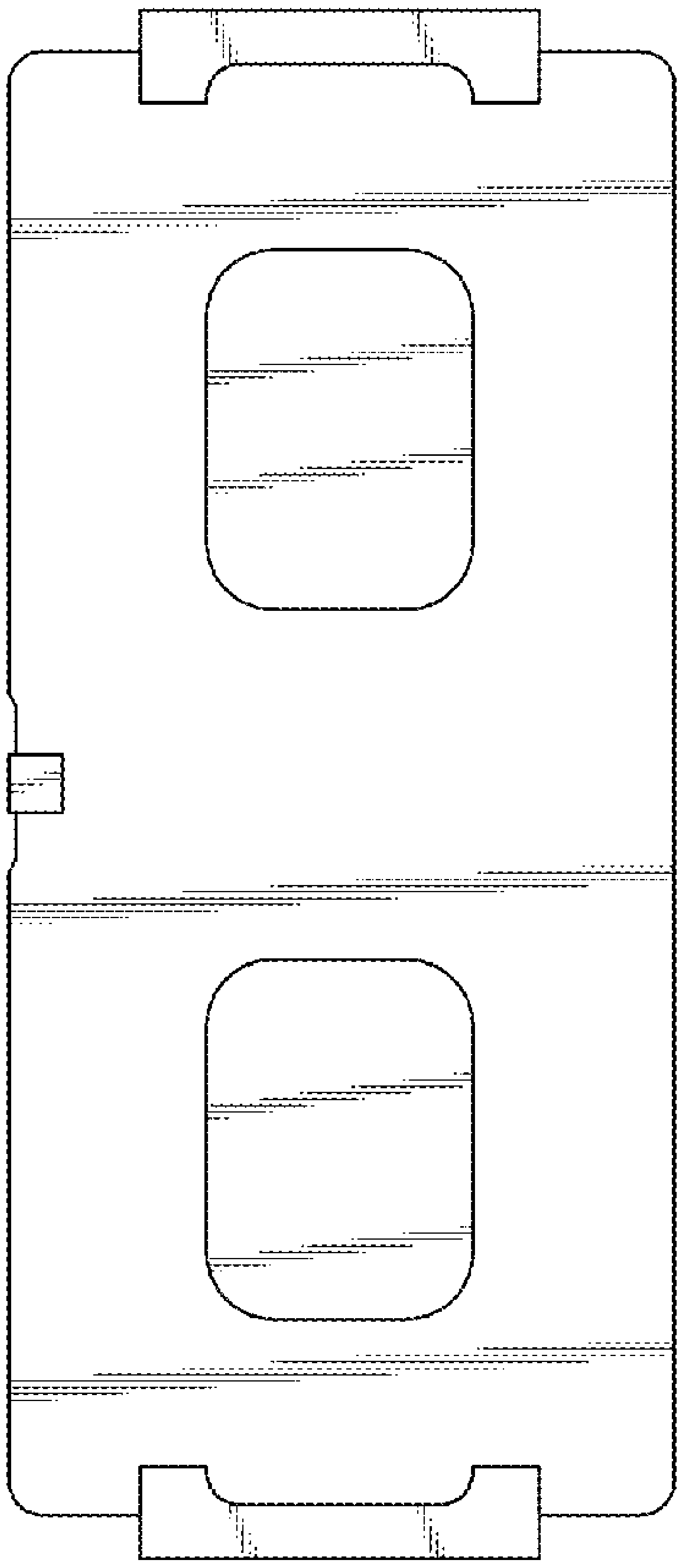


FIG.7

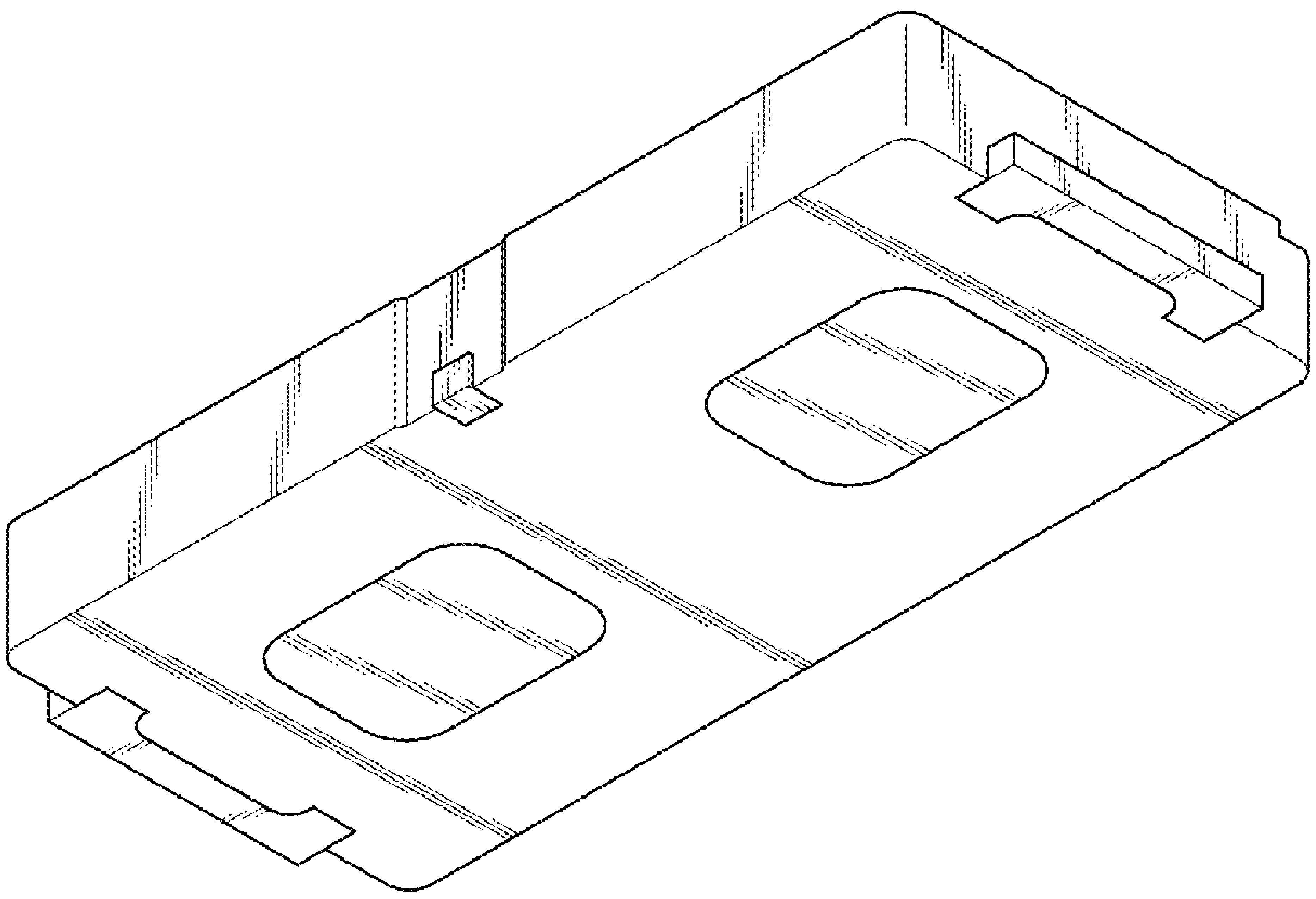


FIG.8